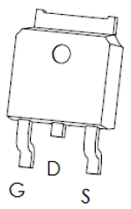
GPT030N04LTF

40V N-Channel MOSFET

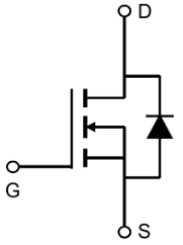
Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
40V	3.2mΩ@10V	90A
	5.2mΩ@10V	

TO-252-2L



Schematic diagram



Feature

- Split Gate Trench Technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- Power Management
- Load Switching
- Motor Driving
- High frequency switching, synchronous rectification

Package Marking and Ordering Information

Part Number	Package	Marking	Packing	Reel Size	Tape Width	Qty
GPT030N04LTF	TO-252-2L	T030N04L	Reel & Tape	330mm	16mm	2500pcs

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	40	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current[1]	T_C = 25°C	I_D	90	A
	T_C = 100°C		57	
Pulsed Drain Current[2]		I_{DM}	360	A
Single Pulsed Avalanche Current[3]		I_{AS}	25	A
Single Pulsed Avalanche Energy[3]		E_{AS}	156	mJ
Power Dissipation[5]	T_C = 25°C	P_D	62.5	W
Thermal Resistance from Junction to Ambient[6]		$R_{\theta JA}$	45	°C/W
Thermal Resistance from Junction to Case		$R_{\theta JC}$	2.0	°C/W
Junction Temperature		T_J	150	°C
Storage Temperature		T_{STG}	-55~ +150	°C

MOSFET ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D = 250μA	40			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 40V, V_{GS} = 0V			1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS} = ±20V, V_{DS} = 0V			±100	nA
On Characteristics[4]						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	1.2	1.8	2.5	V
Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS} = 10V, I_D = 20A		3.2	4.0	mΩ
		V_{GS} = 4.5V, I_D = 15A		5.2	7.5	mΩ
Forward Transconductance	g_{FS}	V_{DS} = 5V, I_D = 20A	25			S
Dynamic Characteristics						
Input Capacitance	C_{iss}	V_{DS} = 20V, V_{GS} = 0V, f = 1MHz		1530		pF
Output Capacitance	C_{oss}			406		
Reverse Transfer Capacitance	C_{rss}			26		
Gate Resistance	R_g	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz		3.3		Ω
Switching Characteristics						
Total Gate Charge	Q_g	V_{DS} = 20V, V_{GS} = 10V, I_D =10A		27		nC
Gate-Source Charge	Q_{gs}			5.0		
Gate-Drain Charge	Q_{gd}			6.5		
Gate Plateau Voltage	$V_{plateau}$			3.0		V
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 20V, V_{GS} = 10V, I_D = 20A, R_G = 3Ω		7		ns
Turn-On Rise Time	t_r			4.4		
Turn-Off Delay Time	$t_{d(off)}$			24		
Turn-Off Fall Time	t_f			5		
Source-Drain Diode Characteristics						
Diode Forward Voltage[4]	V_{SD}	V_{GS} = 0V, I_S = 20A			1.2	V
Diode Continuous Forward Current[1]	I_S	T_C = 25℃			90	A
Diode Pulse Forward Current[2]	I_{SM}	T_C = 25℃			360	A
Diode Reverse Recovery Time	t_{rr}	I_F = 20A, dI/dt = 100A/μs		35		ns
Diode Reverse Recovery Charge	Q_{rr}	I_F = 20A, dI/dt = 100A/μs		20		nC

Notes:

1.The maximum current rating is limited by package. And device mounted on a large heatsink.

2.Pulse Test: Pulse Width ≤ 10μs, duty cycle ≤ 1%.

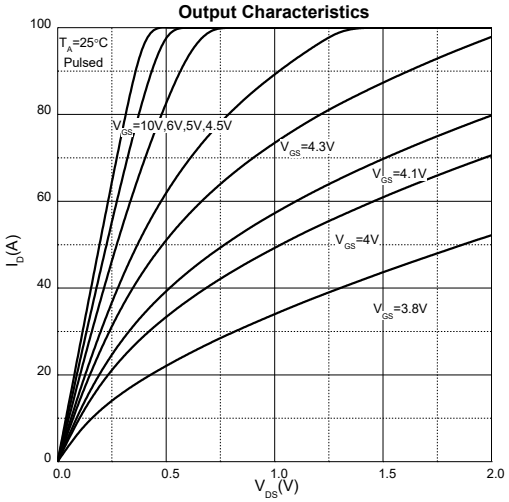
3.E_{AS} condition: V_{DD} = 40V, V_{GS} = 10V, L = 0.5mH, R_G = 25Ω Starting T_J = 25°C.

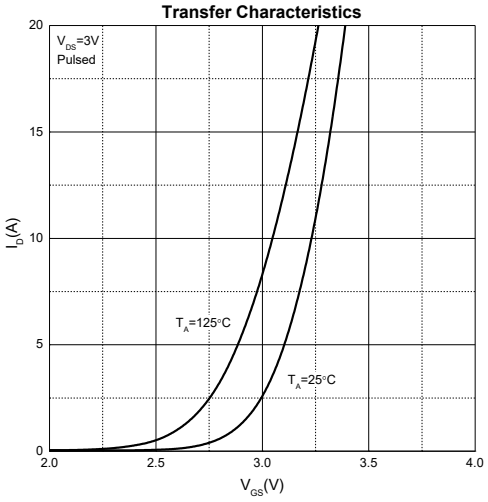
4.Pulse Test: Pulse Width ≤ 300μs, duty cycle ≤ 2%.

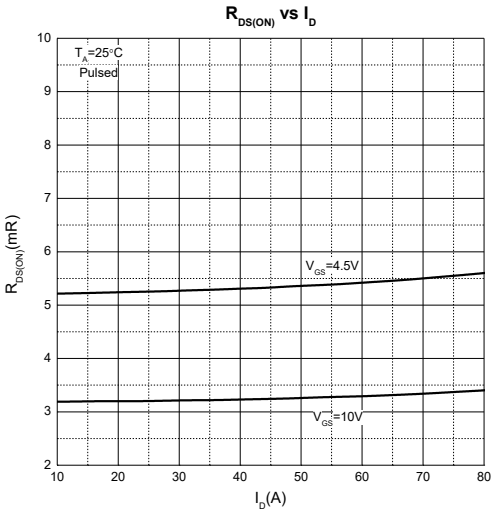
5.The power dissipation P_D is limited by $T_{J(MAX)}$ = 150°C. And device mounted on a large heatsink.

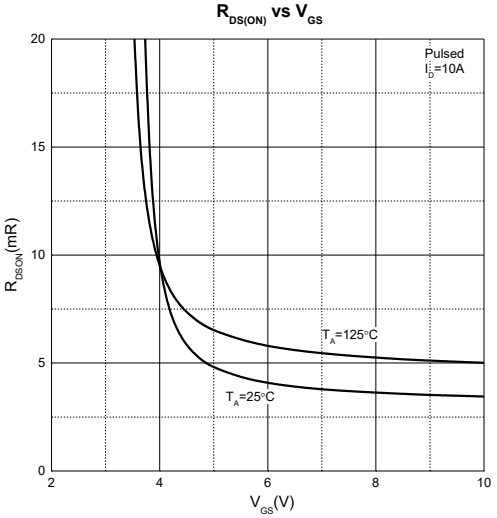
6.Device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A = 25°C.

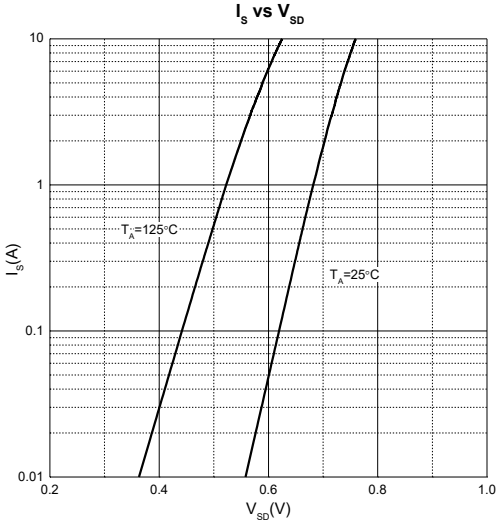
Typical Characteristics

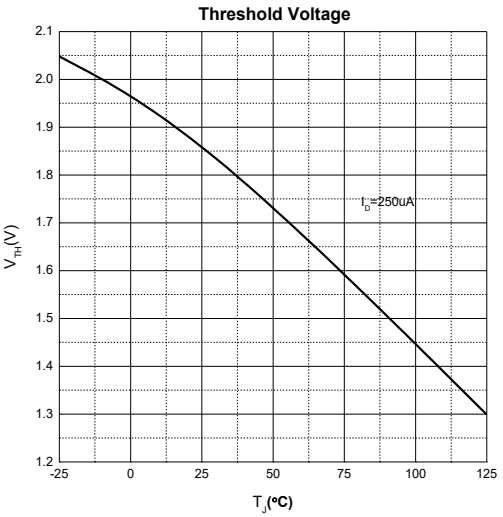


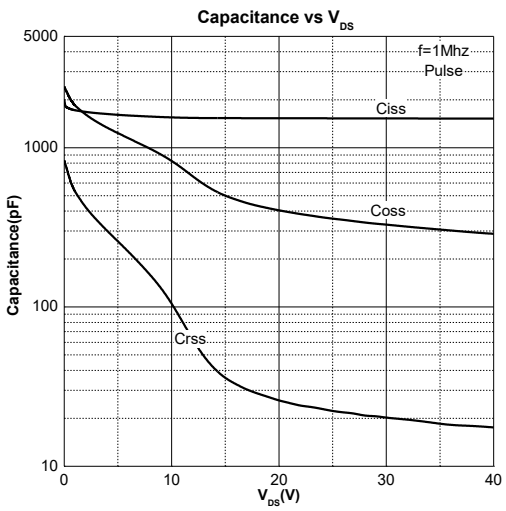


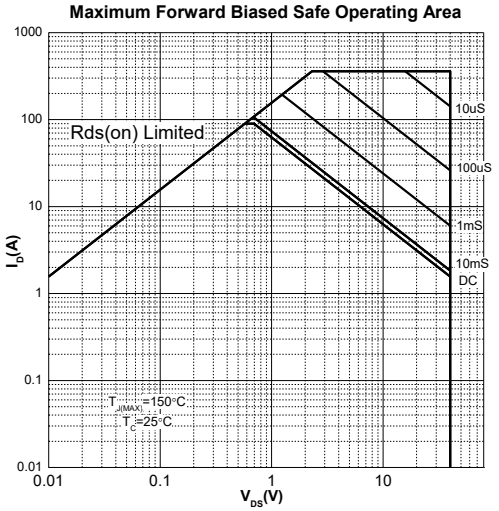


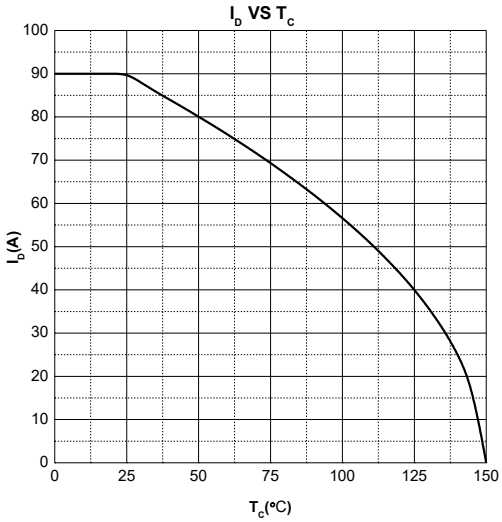


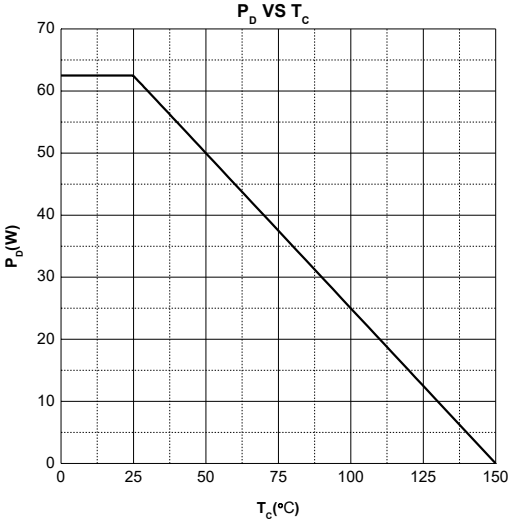


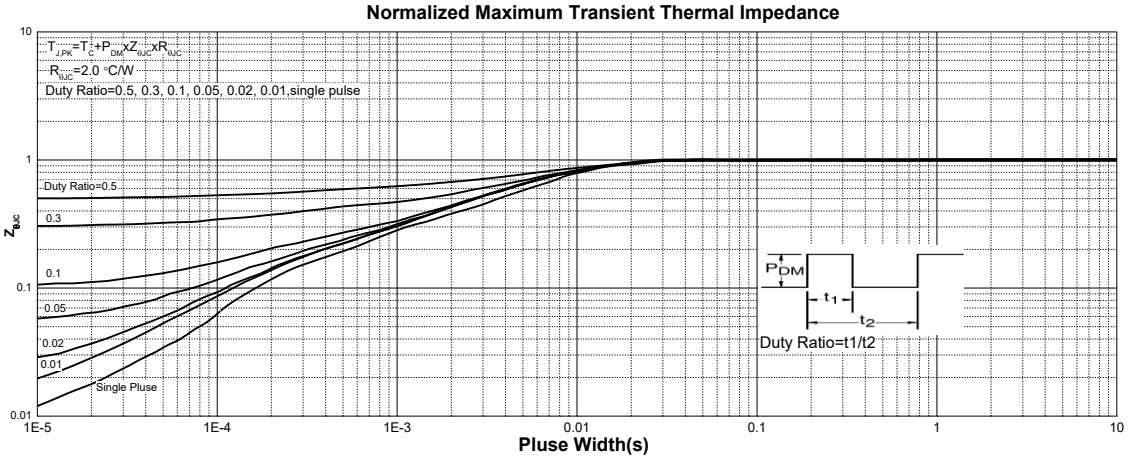



Capacitance vs V_{DS}
f=1Mhz
Pulse
Ciss
Coss
Crss
Capacitance(pF)
V_{DS}(V)


Maximum Forward Biased Safe Operating Area
Rds(on) Limited
10uS
100uS
1mS
10mS
DC
$T_{J(MAX)}$=150°C
T_C=25°C
I_D(A)
V_{DS}(V)

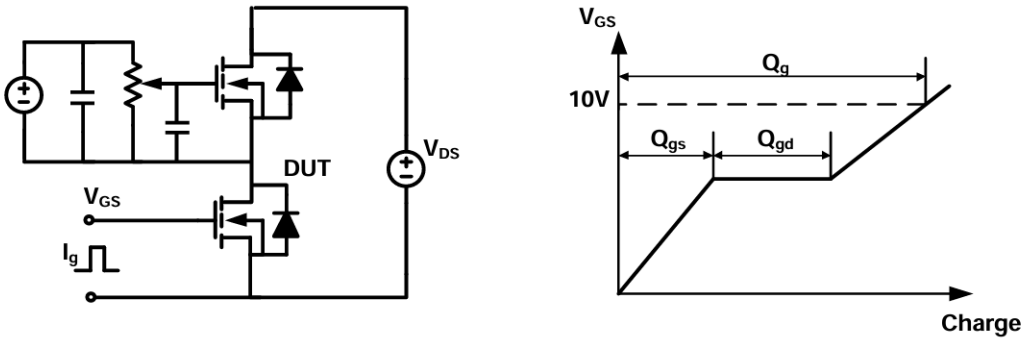

I_D VS T_C
I_D(A)
T_C(°C)


P_D VS T_C
P_D(W)
T_C(°C)

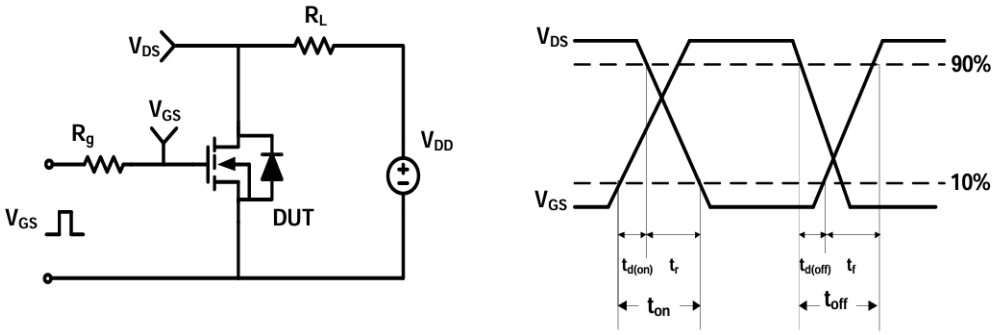

Normalized Maximum Transient Thermal Impedance
$T_{J,PK}=T_C+P_{DM}xZ_{\theta JC}xR_{\theta JC}$
$R_{\theta JC}$=2.0 °C/W
Duty Ratio=0.5, 0.3, 0.1, 0.05, 0.02, 0.01,single pulse
Duty Ratio=0.5
0.3
0.1
0.05
0.02
0.01
Single Pluse
P_{DM}
t_1
t_2
Duty Ratio=t1/t2
$Z_{\theta JC}$
Pluse Width(s)

Test Circuit

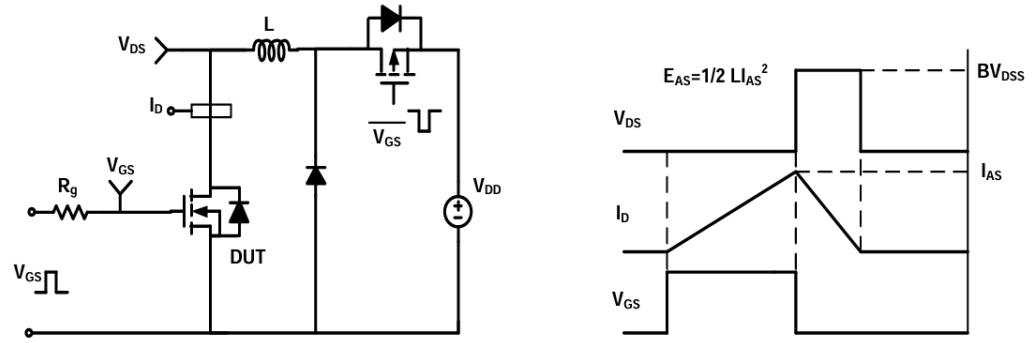
Gate Charge Test Circuit & Waveform



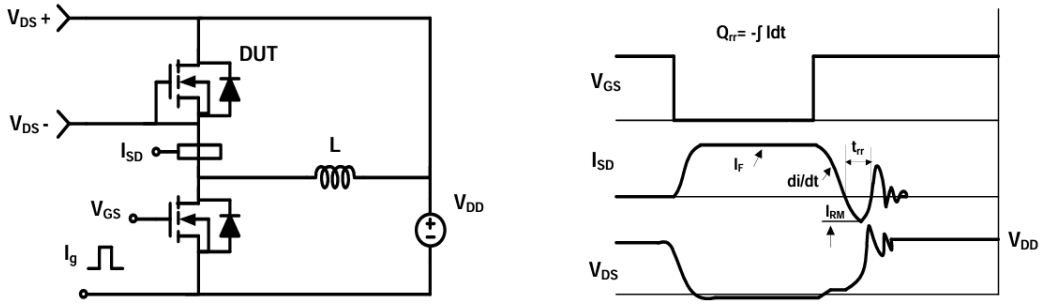
Resistive Switching Test Circuit & Waveform



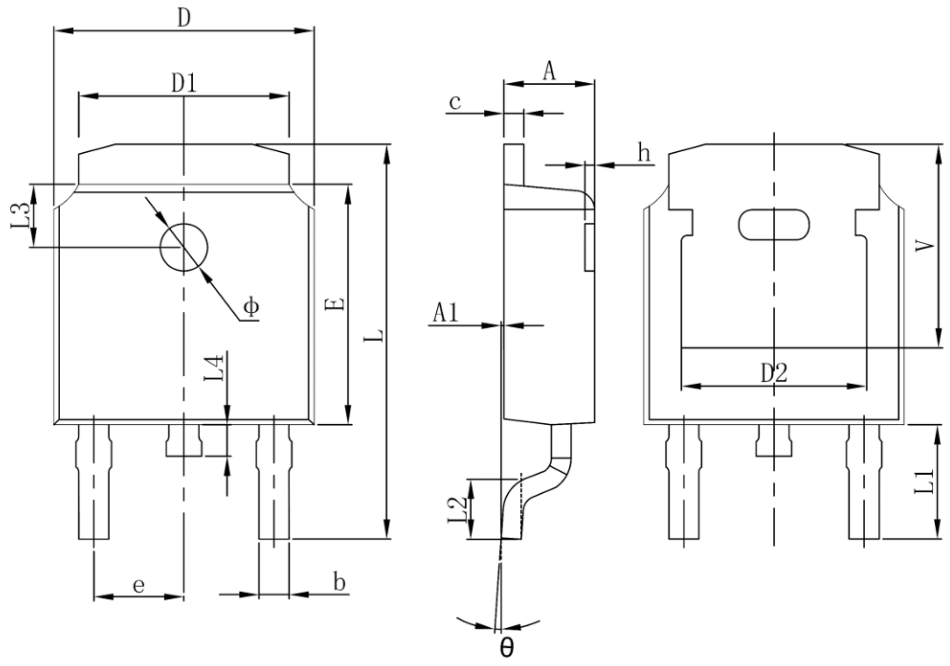
Unclamped Inductive Switching (UIS) Test Circuit & Waveform



Diode Recovery Test Circuit & Waveform



TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.635	0.860	0.025	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830REF		0.190REF	
E	6.000	6.300	0.236	0.248
e	2.186	2.386	0.086	0.094
L	9.712	10.312	0.382	0.406
L1	2.900REF		0.114REF	
L2	1.400	1.700	0.055	0.067
L3	1.600REF		0.063REF	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.250REF		0.207REF	

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